

ELECTRONIC ASSEMBLY STENCIL CLEANING

As electronic components shrink, and PCB assemblies grow denser, consistent solder paste deposits become essential to prevent costly defects. Proper solder paste transfer, especially for small apertures, is critical to maintaining high-quality results. Using the right engineered solvents on your stencils has proven to increase the number of prints between wipes and extend the stencil life on the printer.

Selecting the best stencil cleaning method — whether manual hand wiping, off-line machine cleaning, or on-printer under-stencil wiping — can significantly improve print quality and process yields. With KYZEN's expert guidance and advanced cleaning solutions, you'll get the optimal product tailored to your process, ensuring consistent performance and superior print results.

SUGGESTED PRODUCTS:

KYZEN E5631



KYZEN E5631 is a versatile, cost effective solution used in all types of stencil cleaning processes including spray-in-air, ultrasonic and understencil wipe systems. E5631 is compatible with stencil foil, epoxy adhesives, frames, and mesh as well as the materials of construction found in stencil cleaning equipment.

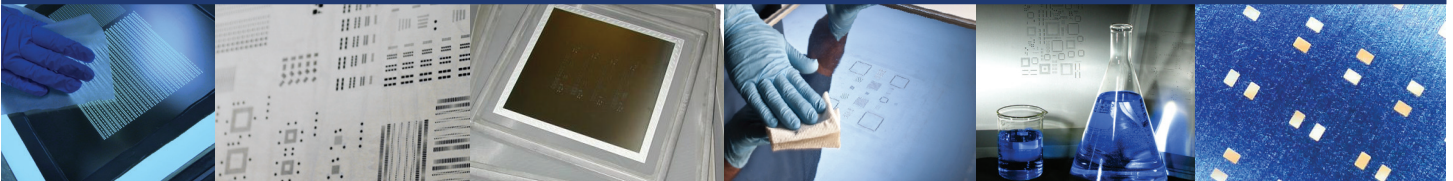
KYZEN E5611

KYZEN E5611 is a cost effective cleaning chemistry designed to be diluted for removing flux, solder paste and uncured adhesives from stencils and misprints. E5611 has proven compatible with most nano coatings and standard stencil cleaning equipment.

APPLICATIONS:

- Ultrasonic & Spray Equipment
- Semi-Automatic and Manual Cleaning
- Removes All Solder Paste Types
- Effectively Cleans Uncured Adhesives
- Does Not Remove Cured Nano Coatings
- Effective for Misprints

- Semi-Automatic and Manual Cleaning
- Fast Drying, Non-Flammable
- Removes All Solder Paste Types
- Effectively Cleans Uncured Adhesives
- Does Not Interact or Remove Nano Coatings
- Effective for Misprints



STENCIL CLEANING - PRINTER UNDERSIDE WIPE

SUGGESTED PRODUCTS:

CYBERSOLV C8882



CYBERSOLV C8882 is a GreenScreen-certified solvent designed for compatibility with stencil printers. C8882 Rapidly dissolves a wide range of flux compositions, significantly improves print yields and creates a more stable and consistent process. Ideal for large board applications and/or designs that wipe every 5 or more prints.

KYZEN E5631J



KYZEN E5631J is a ready-to-use solution engineered specifically for removing raw solder paste from stencils on and off the printer. E5631J cleans all types of raw solder pastes and compatible with all major printer stencil brands. Ideal for applications that require more frequent wiping due to complex geometry.

APPLICATIONS:

- Compatible with All Major Printer Brands
- Non-Flammable IPA Alternative
- Dissolves All Solder Paste Fluxes
- Effectively Removes Uncured Adhesives
- Does Not Interact or Remove Nano Coatings

- Compatible with All Major Printer Brands
- Removes All Solder Paste Types
- Effectively Cleans Uncured Adhesives
- Does Not Remove Nano Coatings
- Fast Drying and Outperforms IPA